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ST72321Rx ST72321ARx ST72321Jx

64/44-pin 8-bit MCU with 32 to 60K Flash/ROM, ADC, five timers, SPI, SCI, I²C interface

Features

■ Memories

- 32K to 60K dual voltage High Density Flash (HDFlash) or ROM with read-out protection capability, In-Application Programming and In-Circuit Programming for HDFlash devices
- 1K to 2K RAM
- HDFlash endurance: 100 cycles, data retention: 40 years at 85°C

■ Clock, Reset And Supply Management

- Enhanced low voltage supervisor (LVD) for main supply and auxiliary voltage detector (AVD) with interrupt capability
- Clock sources: crystal/ceramic resonator oscillators, internal RC oscillator and bypass for external clock
- PLL for 2x frequency multiplication
- Four Power Saving Modes: Halt, Active-Halt, Wait and Slow

■ Interrupt Management

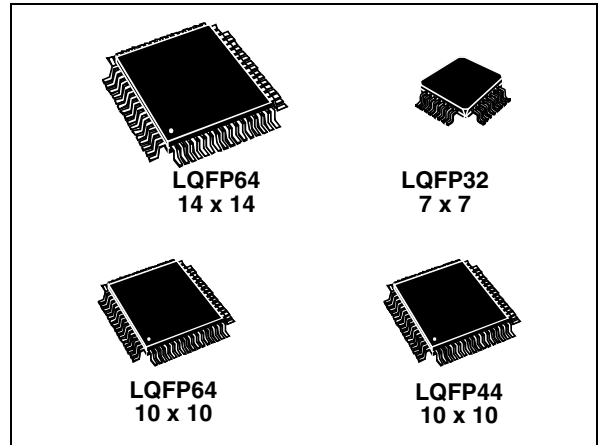
- Nested interrupt controller
- 14 interrupt vectors plus TRAP and RESET
- Top Level Interrupt (TLI) pin on 64-pin devices
- 15/9 external interrupt lines (on 4 vectors)

■ Up to 48 I/O Ports

- 48/32/24 multifunctional bidirectional I/O lines
- 34/22/17 alternate function lines
- 16/12/10 high sink outputs

■ 5 Timers

- Main Clock Controller with: Real time base, Beep and Clock-out capabilities
- Configurable watchdog timer
- Two 16-bit timers with: 2 input captures, 2 output compares, external clock input on one timer, PWM and pulse generator modes



- 8-bit PWM Auto-reload timer with: 2 input captures, 4 PWM outputs, output compare and time base interrupt, external clock with event detector

■ 3 Communications Interfaces

- SPI synchronous serial interface
- SCI asynchronous serial interface
- I²C multimaster interface

■ 1 Analog peripheral

- 10-bit ADC with up to 16 input ports

■ Instruction Set

- 8-bit Data Manipulation
- 63 Basic Instructions
- 17 main Addressing Modes
- 8 x 8 Unsigned Multiply Instruction

■ Development Tools

- Full hardware/software development package
- In-Circuit Testing capability

Table 1. Device summary

Features	ST72321R9/ST72321AR9/ ST72321J9	ST72321R7/ST72321AR7/ ST72321J7	ST72321R6/ST72321AR6
Program memory - bytes	Flash/ROM 60K	Flash/ROM 48K	Flash/ROM 32K
RAM (stack) - bytes	2048 (256)	1536 (256)	1024 (256)
Operating Voltage	3.8 to 5.5V		
Temp. Range	-40 to +125°C, -40 to +85°C		
Package	LQFP64 14x14 (R), LQFP64 10x10 (AR), LQFP44 10x10 (J)		

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1 DESCRIPTION

The ST72F321 Flash and ST72321 ROM devices are members of the ST7 microcontroller family designed for mid-range applications.

All devices are based on a common industry-standard 8-bit core, featuring an enhanced instruction set and are available with Flash or ROM program memory. The ST7 family architecture offers both power and flexibility to software developers, enabling the design of highly efficient and compact application code.

The on-chip peripherals include an A/D converter, a PWM Autoreload timer, 2 general purpose timers, I²C bus, SPI interface and an SCI interface.

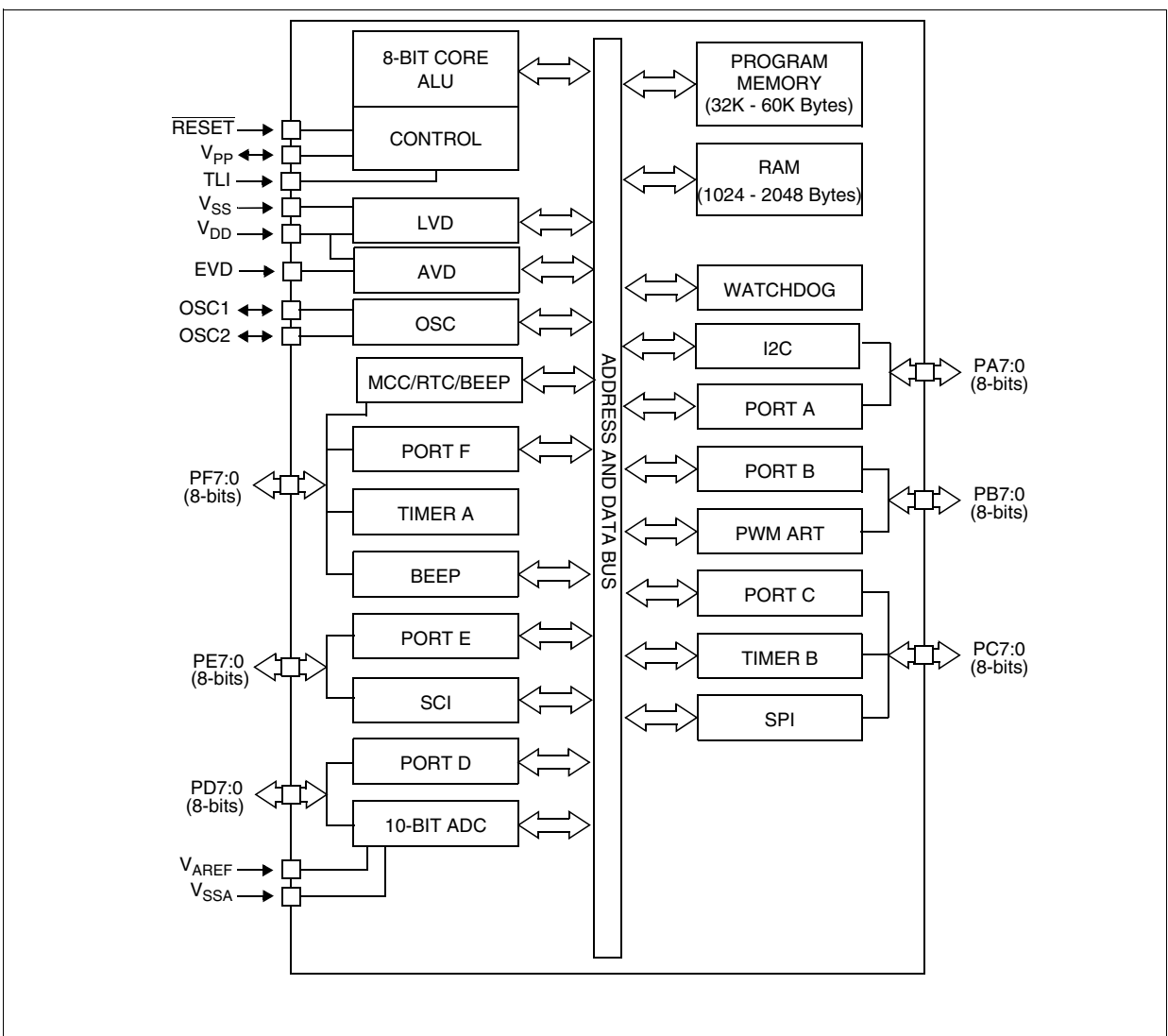
For power economy, microcontroller can switch dynamically into WAIT, SLOW, ACTIVE-HALT or HALT mode when the application is in idle or stand-by state.

Typical applications are consumer, home, office and industrial products.

Related Documentation

AN1131: Migrating applications from ST72511/311/314 to ST72521/321/324

Figure 1. Device Block Diagram



2 PIN DESCRIPTION

Figure 2. 64-Pin LQFP 14x14 and 10x10 Package Pinout

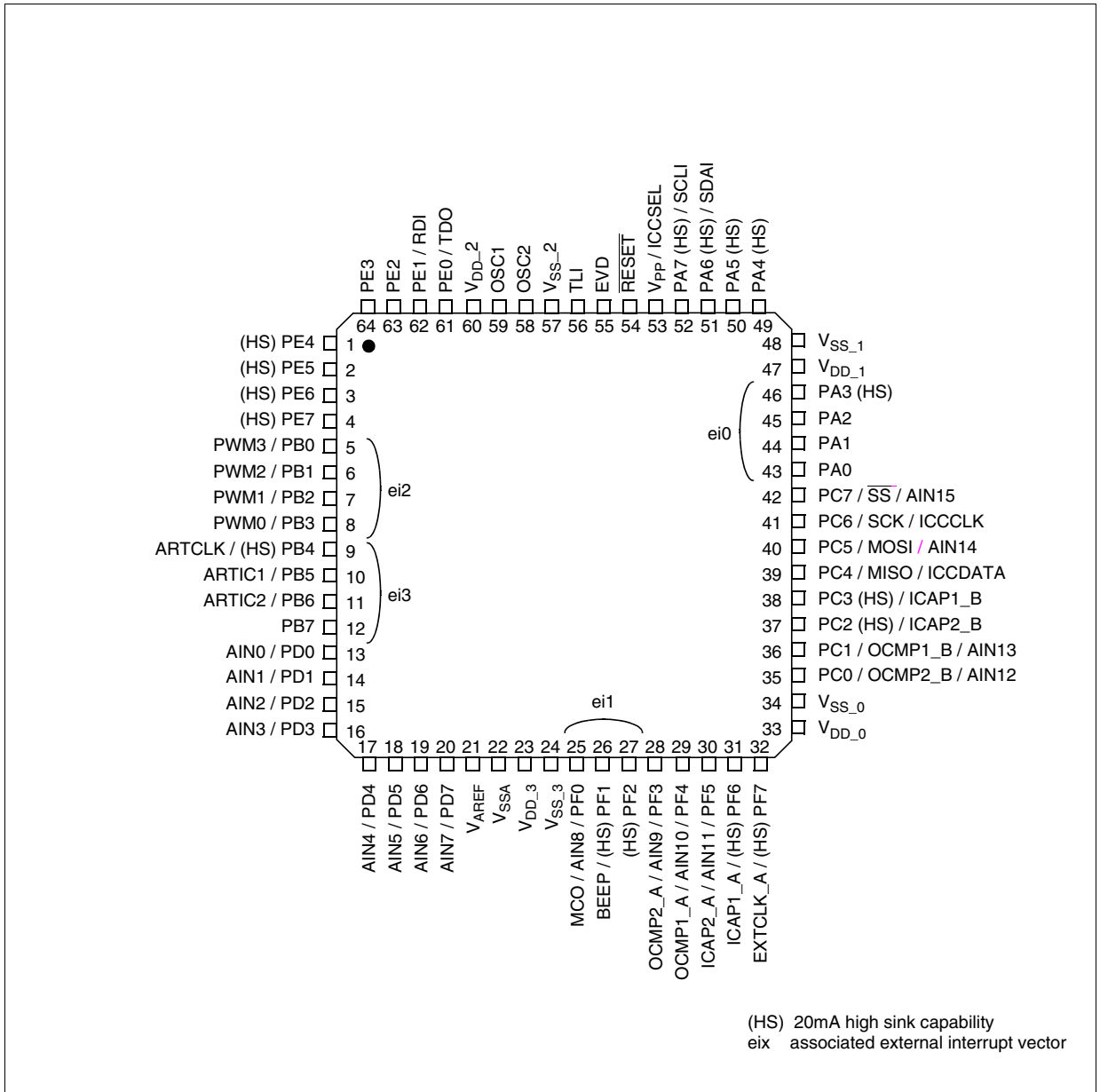
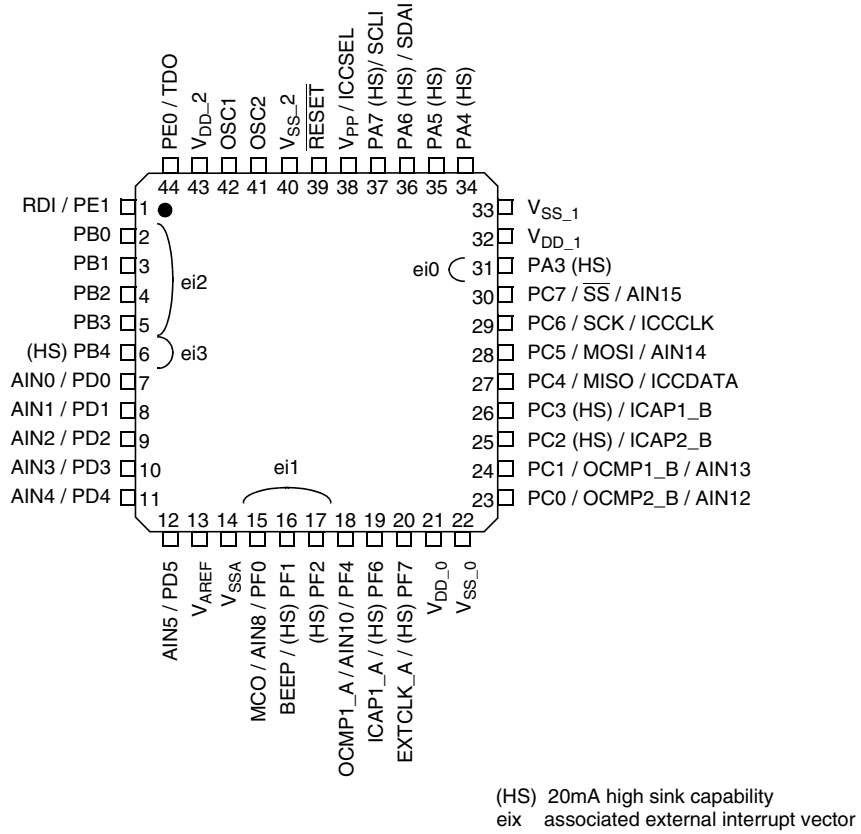


Figure 3. 44-Pin LQFP Package Pinout



PIN DESCRIPTION (Cont'd)

For external pin connection guidelines, refer to See “ELECTRICAL CHARACTERISTICS” on page 138.

Legend / Abbreviations for Table 2 :

Type: I = input, O = output, S = supply

Input level: A = Dedicated analog input

In/Output level: C = CMOS 0.3V_{DD}/0.7V_{DD}
 C_T= CMOS 0.3V_{DD}/0.7V_{DD} with input trigger
 T_T= TTL 0.8V / 2V with Schmitt trigger

Output level: HS = 20mA high sink (on N-buffer only)

Port and control configuration:

- Input: float = floating, wpu = weak pull-up, int = interrupt ¹⁾, ana = analog
- Output: OD = open drain ²⁾, PP = push-pull

Refer to “**I/O PORTS**” on page 46 for more details on the software configuration of the I/O ports.

The RESET configuration of each pin is shown in bold. This configuration is valid as long as the device is in reset state.

Table 2. Device Pin Description

Pin n°			Pin Name	Type	Level		Port						Main function (after reset)	Alternate function
LQFP64	LQFP44	LQFP32			Input	Output	Input				Output			
							float	wpu	int	ana	OD	PP		
1	-	-	PE4 (HS)	I/O	C _T	HS	X	X			X	X	Port E4	
2	-	-	PE5 (HS)	I/O	C _T	HS	X	X			X	X	Port E5	
3	-	-	PE6 (HS)	I/O	C _T	HS	X	X			X	X	Port E6	
4	-	-	PE7 (HS)	I/O	C _T	HS	X	X			X	X	Port E7	
5	2	28	PB0/PWM3	I/O	C _T		X		ei2		X	X	Port B0	PWM Output 3
6	3	-	PB1/PWM2	I/O	C _T		X		ei2		X	X	Port B1	PWM Output 2
7	4	-	PB2/PWM1	I/O	C _T		X		ei2		X	X	Port B2	PWM Output 1
8	5	29	PB3/PWM0	I/O	C _T		X		ei2		X	X	Port B3	PWM Output 0
9	6	30	PB4 (HS)/ARTCLK	I/O	C _T	HS	X		ei3		X	X	Port B4	PWM-ART External Clock
10	-	-	PB5 / ARTIC1	I/O	C _T		X		ei3		X	X	Port B5	PWM-ART Input Capture 1
11	-	-	PB6 / ARTIC2	I/O	C _T		X		ei3		X	X	Port B6	PWM-ART Input Capture 2
12	-	-	PB7	I/O	C _T		X		ei3		X	X	Port B7	
13	7	31	PD0/AIN0	I/O	C _T		X	X		X	X	X	Port D0	ADC Analog Input 0
14	8	32	PD1/AIN1	I/O	C _T		X	X		X	X	X	Port D1	ADC Analog Input 1
15	9	-	PD2/AIN2	I/O	C _T		X	X		X	X	X	Port D2	ADC Analog Input 2
16	10	-	PD3/AIN3	I/O	C _T		X	X		X	X	X	Port D3	ADC Analog Input 3
17	11	-	PD4/AIN4	I/O	C _T		X	X		X	X	X	Port D4	ADC Analog Input 4
18	12	-	PD5/AIN5	I/O	C _T		X	X		X	X	X	Port D5	ADC Analog Input 5
19	-	-	PD6/AIN6	I/O	C _T		X	X		X	X	X	Port D6	ADC Analog Input 6
20	-	-	PD7/AIN7	I/O	C _T		X	X		X	X	X	Port D7	ADC Analog Input 7
21	13	1	V _{AREF}	I										Analog Reference Voltage for ADC
22	14	2	V _{SSA}	S										Analog Ground Voltage

Pin n°			Pin Name	Type	Level		Port						Main function (after reset)	Alternate function	
LQFP64	LQFP44	LQFP32			Input	Output	Input				Output				
							float	wpu	int	ana	OD	PP			
23	-	-	V _{DD_3}	S									Digital Main Supply Voltage		
24	-	-	V _{SS_3}	S									Digital Ground Voltage		
25	15	3	PF0/MCO/AIN8	I/O	C _T		X	ei1	X	X	X	Port F0	Main clock out (f _{OSC} /2)	ADC Analog Input 8	
26	16	4	PF1 (HS)/BEEP	I/O	C _T	HS	X	ei1		X	X	Port F1	Beep signal output		
27	17	-	PF2 (HS)	I/O	C _T	HS	X	ei1		X	X	Port F2			
28	-	-	PF3/OCMP2_A/AIN9	I/O	C _T		X	X		X	X	Port F3	Timer A Output Compare 2	ADC Analog Input 9	
29	18	5	PF4/OCMP1_A/AIN10	I/O	C _T		X	X		X	X	Port F4	Timer A Output Compare 1	ADC Analog Input 10	
30	-	-	PF5/ICAP2_A/AIN11	I/O	C _T		X	X		X	X	Port F5	Timer A Input Capture 2	ADC Analog Input 11	
31	19	6	PF6 (HS)/ICAP1_A	I/O	C _T	HS	X	X		X	X	Port F6	Timer A Input Capture 1		
32	20	7	PF7 (HS)/EXTCLK_A	I/O	C _T	HS	X	X		X	X	Port F7	Timer A External Clock Source		
33	21	-	V _{DD_0}	S									Digital Main Supply Voltage		
34	22	-	V _{SS_0}	S									Digital Ground Voltage		
35	23	8	PC0/OCMP2_B/AIN12	I/O	C _T		X	X		X	X	Port C0	Timer B Output Compare 2	ADC Analog Input 12	
36	24	9	PC1/OCMP1_B/AIN13	I/O	C _T		X	X		X	X	Port C1	Timer B Output Compare 1	ADC Analog Input 13	
37	25	10	PC2 (HS)/ICAP2_B	I/O	C _T	HS	X	X		X	X	Port C2	Timer B Input Capture 2		
38	26	11	PC3 (HS)/ICAP1_B	I/O	C _T	HS	X	X		X	X	Port C3	Timer B Input Capture 1		
39	27	12	PC4/MISO/ICCDATA	I/O	C _T		X	X		X	X	Port C4	SPI Master In / Slave Out Data	ICC Data Input	
40	28	13	PC5/MOSI/AIN14	I/O	C _T		X	X		X	X	Port C5	SPI Master Out / Slave In Data	ADC Analog Input 14	
41	29	29	PC6/SCK/ICCCLK	I/O	C _T		X	X		X	X	Port C6	SPI Serial Clock	ICC Clock Output	
42	30	15	PC7/ \overline{SS} /AIN15	I/O	C _T		X	X		X	X	Port C7	SPI Slave Select (active low)	ADC Analog Input 15	
43	-	-	PA0	I/O	C _T		X	ei0		X	X	Port A0			
44	-	-	PA1	I/O	C _T		X	ei0		X	X	Port A1			

Pin n°			Pin Name	Type	Level		Port						Main function (after reset)	Alternate function
LQFP64	LQFP44	LQFP32			Input	Output	Input				Output			
							float	wpu	int	ana	OD	PP		
45	-	-	PA2	I/O	C _T		X	ei0			X	X	Port A2	
46	31	16	PA3 (HS)	I/O	C _T	HS	X		ei0		X	X	Port A3	
47	32	-	V _{DD_1}	S									Digital Main Supply Voltage	
48	33	-	V _{SS_1}	S									Digital Ground Voltage	
49	34	17	PA4 (HS)	I/O	C _T	HS	X	X			X	X	Port A4	
50	35	-	PA5 (HS)	I/O	C _T	HS	X	X			X	X	Port A5	
51	36	18	PA6 (HS)/SDAI	I/O	C _T	HS	X				T		Port A6	I ² C Data ¹⁾
52	37	19	PA7 (HS)/SCLI	I/O	C _T	HS	X				T		Port A7	I ² C Clock ¹⁾
53	38	20	V _{PP} / ICCSEL	I									Must be tied low. In flash programming mode, this pin acts as the programming voltage input V _{PP} . See Section 12.9.2 for more details. High voltage must not be applied to ROM devices	
54	39	21	RESET	I/O	C _T								Top priority non maskable interrupt.	
55	-	-	EVD										External voltage detector	
56	-	-	TLI	I	C _T				X				Top level interrupt input pin	
57	40	22	V _{SS_2}	S									Digital Ground Voltage	
58	41	23	OSC2 ³⁾	I/O									Resonator oscillator inverter output	
59	42	24	OSC1 ³⁾	I									External clock input or Resonator oscillator inverter input	
60	43	25	V _{DD_2}	S									Digital Main Supply Voltage	
61	44	26	PE0/TDO	I/O	C _T		X	X			X	X	Port E0	SCI Transmit Data Out
62	1	27	PE1/RDI	I/O	C _T		X	X			X	X	Port E1	SCI Receive Data In
63	-	-	PE2 (Flash device)	I/O	C _T			X					Port E2 Caution: In Flash devices this port is always input with weak pull-up.	
			PE2 (ROM device)				X			X	X	Port E2 Caution: In ROM devices, no weak pull-up present on this port. In LQFP44 this pin is not connected to an internal pull-up like other unbonded pins (See note 4). It is recommended to configure it as output push pull to avoid added current consumption.		
64	-	-	PE3	I/O	C _T		X	X			X	X	Port E3	

Notes:

1. In the interrupt input column, “eiX” defines the associated external interrupt vector. If the weak pull-up column (wpu) is merged with the interrupt column (int), then the I/O configuration is pull-up interrupt input, else the configuration is floating interrupt input.

2. In the open drain output column, “T” defines a true open drain I/O (P-Buffer and protection diode to V_{DD} are not implemented). See “I/O PORTS” on page 46. and [Section 12.8 I/O PORT PIN CHARACTER-](#)

[ISTICS](#) for more details.

3. OSC1 and OSC2 pins connect a crystal/ceramic resonator, or an external source to the on-chip oscillator; see [Section 1 DESCRIPTION](#) and [Section 12.5 CLOCK AND TIMING CHARACTERISTICS](#) for more details.

4. On the chip, each I/O port may have up to 8 pads:

– ads that are not bonded to external pins are forced by hardware in input pull-up configuration after reset. The configuration of these pads must be kept at reset state to avoid added current consumption.

5. Pull-up always activated on PE2 see limitation [Section 15.4.6](#).

6. It is mandatory to connect all available V_{DD} and V_{REF} pins to the supply voltage and all V_{SS} and V_{SSA} pins to ground.

3 REGISTER & MEMORY MAP

As shown in [Figure 4](#), the MCU is capable of addressing 64K bytes of memories and I/O registers. The available memory locations consist of 128 bytes of register locations, up to 2Kbytes of RAM and up to 60Kbytes of user program memory. The RAM space includes up to 256 bytes for the stack from 0100h to 01FFh.

The highest address bytes contain the user reset and interrupt vectors.

IMPORTANT: Memory locations marked as “Reserved” must never be accessed. Accessing a reserved area can have unpredictable effects on the device.

Related Documentation

AN 985: Executing Code in ST7 RAM

Figure 4. Memory Map

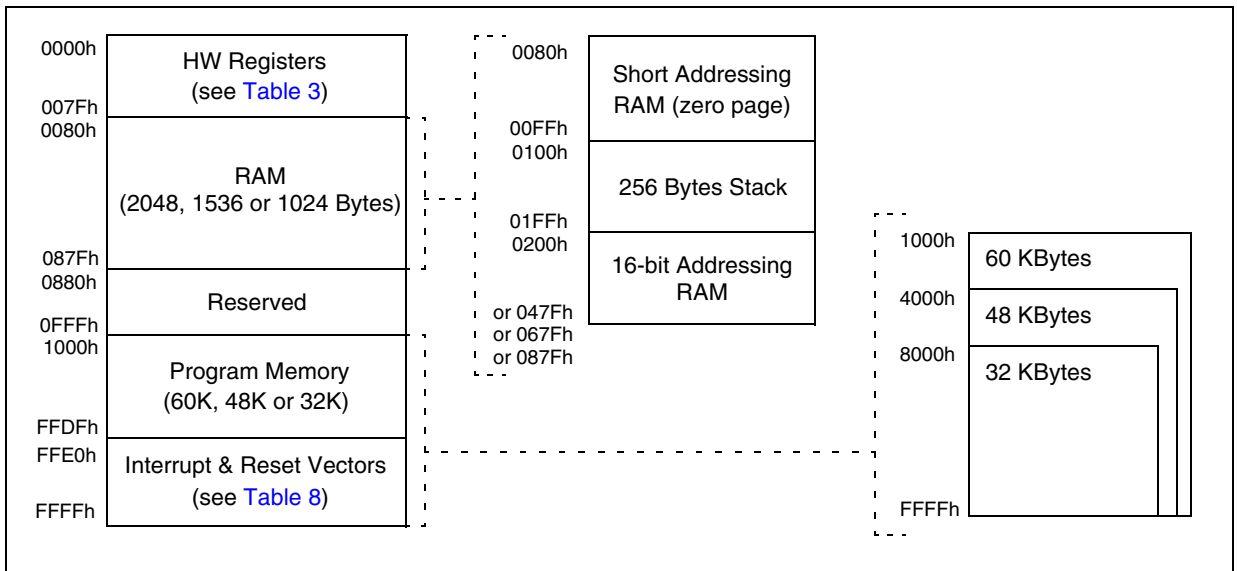


Table 3. Hardware Register Map

Address	Block	Register Label	Register Name	Reset Status	Remarks
0000h 0001h 0002h	Port A ²⁾	PADR PADDR PAOR	Port A Data Register Port A Data Direction Register Port A Option Register	00h ¹⁾ 00h 00h	R/W R/W R/W
0003h 0004h 0005h	Port B ²⁾	PBDR PBDDR PBOR	Port B Data Register Port B Data Direction Register Port B Option Register	00h ¹⁾ 00h 00h	R/W R/W R/W
0006h 0007h 0008h	Port C	PCDR PCDDR PCOR	Port C Data Register Port C Data Direction Register Port C Option Register	00h ¹⁾ 00h 00h	R/W R/W R/W
0009h 000Ah 000Bh	Port D ²⁾	PDDR PDDDR PDOR	Port D Data Register Port D Data Direction Register Port D Option Register	00h ¹⁾ 00h 00h	R/W R/W R/W
000Ch 000Dh 000Eh	Port E ²⁾	PEDR PEDDR PEOR	Port E Data Register Port E Data Direction Register Port E Option Register	00h ¹⁾ 00h 00h	R/W R/W ²⁾ R/W ²⁾
000Fh 0010h 0011h	Port F ²⁾	PFDR PFDDR PFOR	Port F Data Register Port F Data Direction Register Port F Option Register	00h ¹⁾ 00h 00h	R/W R/W R/W
0012h to 0017h	Reserved Area (6 Bytes)				
0018h 0019h 001Ah 001Bh 001Ch 001Dh 001Eh	I ² C	I ² CCR I ² CSR1 I ² CSR2 I ² CCCR I ² COAR1 I ² COAR2 I ² CDR	I ² C Control Register I ² C Status Register 1 I ² C Status Register 2 I ² C Clock Control Register I ² C Own Address Register 1 I ² C Own Address Register2 I ² C Data Register	00h 00h 00h 00h 00h 00h 00h	R/W Read Only Read Only R/W R/W R/W R/W
001Fh 0020h	Reserved Area (2 Bytes)				
0021h 0022h 0023h	SPI	SPIDR SPICR SPICSR	SPI Data I/O Register SPI Control Register SPI Control/Status Register	xxh 0xh 00h	R/W R/W R/W
0024h 0025h 0026h 0027h	ITC	ISPR0 ISPR1 ISPR2 ISPR3	Interrupt Software Priority Register 0 Interrupt Software Priority Register 1 Interrupt Software Priority Register 2 Interrupt Software Priority Register 3	FFh FFh FFh FFh	R/W R/W R/W R/W
0028h		EICR	External Interrupt Control Register	00h	R/W
0029h	FLASH	FCSR	Flash Control/Status Register	00h	R/W

Address	Block	Register Label	Register Name	Reset Status	Remarks
002Ah	WATCHDOG	WDGCR	Watchdog Control Register	7Fh	R/W
002Bh		SICSR	System Integrity Control/Status Register	000x 000x b	R/W
002Ch 002Dh	MCC	MCCSR MCCBCR	Main Clock Control / Status Register Main Clock Controller: Beep Control Register	00h 00h	R/W R/W
002Eh to 0030h	Reserved Area (3 Bytes)				
0031h 0032h 0033h 0034h 0035h 0036h 0037h 0038h 0039h 003Ah 003Bh 003Ch 003Dh 003Eh 003Fh	TIMER A	TACR2 TACR1 TACSR TAIC1HR TAIC1LR TAOC1HR TAOC1LR TACHR TACL TAACHR TAACL TAIC2HR TAIC2LR TAOC2HR TAOC2LR	Timer A Control Register 2 Timer A Control Register 1 Timer A Control/Status Register Timer A Input Capture 1 High Register Timer A Input Capture 1 Low Register Timer A Output Compare 1 High Register Timer A Output Compare 1 Low Register Timer A Counter High Register Timer A Counter Low Register Timer A Alternate Counter High Register Timer A Alternate Counter Low Register Timer A Input Capture 2 High Register Timer A Input Capture 2 Low Register Timer A Output Compare 2 High Register Timer A Output Compare 2 Low Register	00h 00h xxxx x0xx b xxh xxh 80h 00h FFh FCh FFh FCh xxh xxh 80h 00h	R/W R/W R/W Read Only Read Only R/W R/W Read Only Read Only Read Only Read Only Read Only Read Only R/W R/W
0040h	Reserved Area (1 Byte)				
0041h 0042h 0043h 0044h 0045h 0046h 0047h 0048h 0049h 004Ah 004Bh 004Ch 004Dh 004Eh 004Fh	TIMER B	TBCR2 TBCR1 TBCSR TBIC1HR TBIC1LR TBOC1HR TBOC1LR TBCHR TBCLR TBACHR TBACL TBIC2HR TBIC2LR TBOC2HR TBOC2LR	Timer B Control Register 2 Timer B Control Register 1 Timer B Control/Status Register Timer B Input Capture 1 High Register Timer B Input Capture 1 Low Register Timer B Output Compare 1 High Register Timer B Output Compare 1 Low Register Timer B Counter High Register Timer B Counter Low Register Timer B Alternate Counter High Register Timer B Alternate Counter Low Register Timer B Input Capture 2 High Register Timer B Input Capture 2 Low Register Timer B Output Compare 2 High Register Timer B Output Compare 2 Low Register	00h 00h xxxx x0xx b xxh xxh 80h 00h FFh FCh FFh FCh xxh xxh 80h 00h	R/W R/W R/W Read Only Read Only R/W R/W Read Only Read Only Read Only Read Only Read Only R/W R/W
0050h 0051h 0052h 0053h 0054h 0055h 0056h 0057h	SCI	SCISR SCIDR SCIBRR SCICR1 SCICR2 SCIERPR SCIETPR	SCI Status Register SCI Data Register SCI Baud Rate Register SCI Control Register 1 SCI Control Register 2 SCI Extended Receive Prescaler Register Reserved area SCI Extended Transmit Prescaler Register	C0h xxh 00h x000 0000b 00h 00h --- 00h	Read Only R/W R/W R/W R/W R/W --- R/W

Address	Block	Register Label	Register Name	Reset Status	Remarks
0058h to 006Fh	Reserved Area (24 Bytes)				
0070h 0071h 0072h	ADC	ADCCSR ADCDRH ADCDRL	Control/Status Register Data High Register Data Low Register	00h 00h 00h	R/W Read Only Read Only
0073h 0074h 0075h 0076h 0077h 0078h 0079h 007Ah 007Bh 007Ch 007Dh	PWM ART	PWMDCR3 PWMDCR2 PWMDCR1 PWMDCR0 PWMCR ARTCSR ARTCAR ARTARR ARTICCSR ARTICR1 ARTICR2	PWM AR Timer Duty Cycle Register 3 PWM AR Timer Duty Cycle Register 2 PWM AR Timer Duty Cycle Register 1 PWM AR Timer Duty Cycle Register 0 PWM AR Timer Control Register Auto-Reload Timer Control/Status Register Auto-Reload Timer Counter Access Register Auto-Reload Timer Auto-Reload Register AR Timer Input Capture Control/Status Reg. AR Timer Input Capture Register 1 AR Timer Input Capture Register 1	00h 00h 00h 00h 00h 00h 00h 00h 00h 00h 00h	R/W R/W R/W R/W R/W R/W R/W R/W R/W Read Only Read Only
007Eh 007Fh	Reserved Area (2 Bytes)				

Legend: x=undefined, R/W=read/write

Notes:

1. The contents of the I/O port DR registers are readable only in output configuration. In input configuration, the values of the I/O pins are returned instead of the DR register contents.
2. The bits associated with unavailable pins must always keep their reset value.

4 FLASH PROGRAM MEMORY

4.1 Introduction

The ST7 dual voltage High Density Flash (HDFlash) is a non-volatile memory that can be electrically erased as a single block or by individual sectors and programmed on a Byte-by-Byte basis using an external V_{PP} supply.

The HDFlash devices can be programmed and erased off-board (plugged in a programming tool) or on-board using ICP (In-Circuit Programming) or IAP (In-Application Programming).

The array matrix organisation allows each sector to be erased and reprogrammed without affecting other sectors.

4.2 Main Features

- Three Flash programming modes:
 - Insertion in a programming tool. In this mode, all sectors including option bytes can be programmed or erased.
 - ICP (In-Circuit Programming). In this mode, all sectors including option bytes can be programmed or erased without removing the device from the application board.
 - IAP (In-Application Programming) In this mode, all sectors except Sector 0, can be programmed or erased without removing the device from the application board and while the application is running.
- ICT (In-Circuit Testing) for downloading and executing user application test patterns in RAM
- Read-out protection
- Register Access Security System (RASS) to prevent accidental programming or erasing

4.3 Structure

The Flash memory is organised in sectors and can be used for both code and data storage.

Depending on the overall Flash memory size in the microcontroller device, there are up to three user

sectors (see Table 4). Each of these sectors can be erased independently to avoid unnecessary erasing of the whole Flash memory when only a partial erasing is required.

The first two sectors have a fixed size of 4 Kbytes (see Figure 5). They are mapped in the upper part of the ST7 addressing space so the reset and interrupt vectors are located in Sector 0 (F000h-FFFFh).

Table 4. Sectors available in Flash devices

Flash Size (bytes)	Available Sectors
4K	Sector 0
8K	Sectors 0,1
> 8K	Sectors 0,1, 2

4.3.1 Read-out Protection

Read-out protection, when selected, provides a protection against Program Memory content extraction and against write access to Flash memory. Even if no protection can be considered as totally unbreakable, the feature provides a very high level of protection for a general purpose microcontroller.

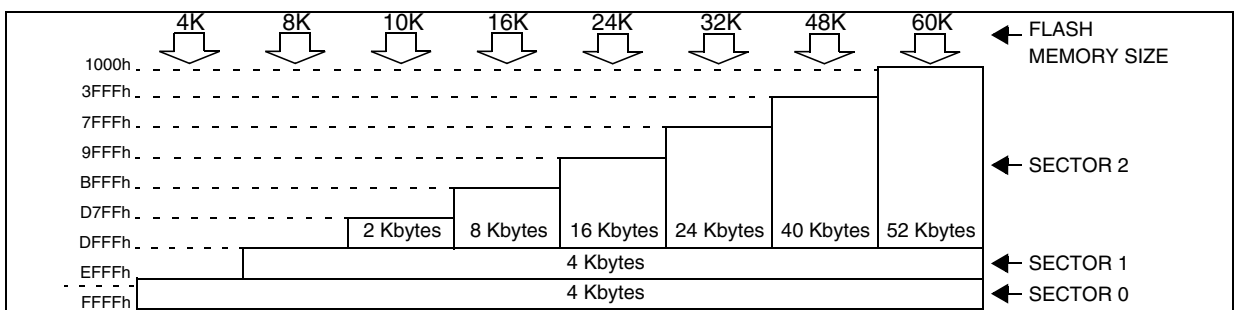
In flash devices, this protection is removed by reprogramming the option. In this case, the entire program memory is first automatically erased and the device can be reprogrammed.

Read-out protection selection depends on the device type:

- In Flash devices it is enabled and removed through the FMP_R bit in the option byte.
- In ROM devices it is enabled by mask option specified in the Option List.

Note: In flash devices, the LVD is not supported if read-out protection is enabled.

Figure 5. Memory Map and Sector Address



FLASH PROGRAM MEMORY (Cont'd)

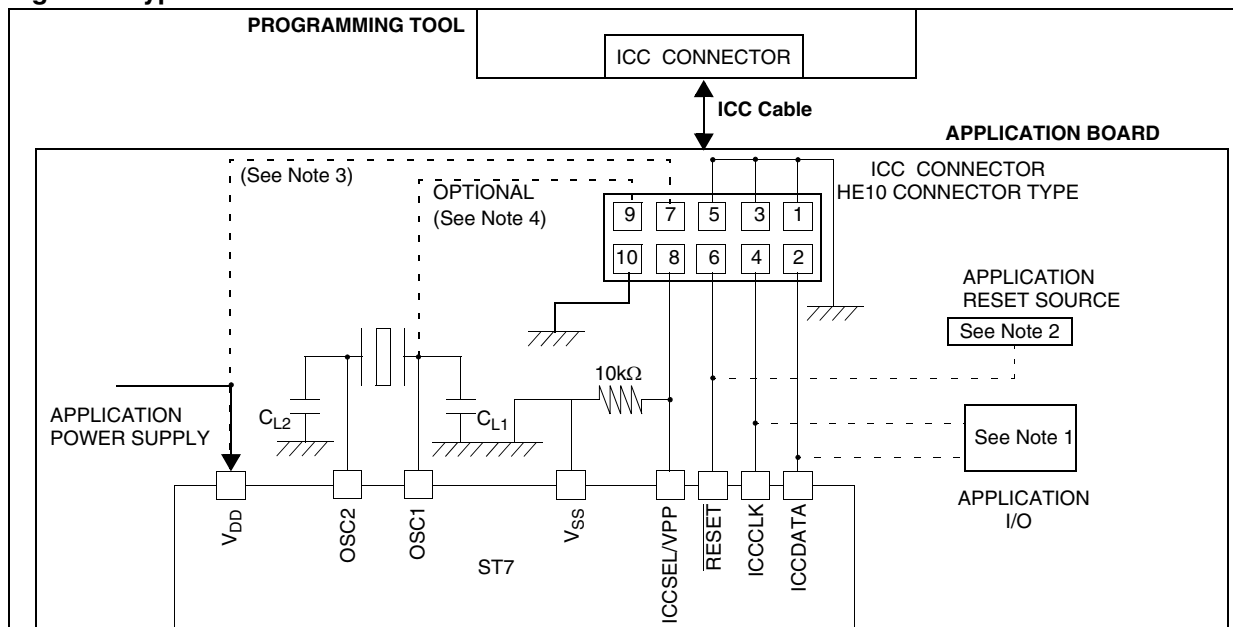
4.4 ICC Interface

ICC needs a minimum of 4 and up to 6 pins to be connected to the programming tool (see Figure 6). These pins are:

- $\overline{\text{RESET}}$: device reset
- V_{SS} : device power supply ground

- ICCCLK: ICC output serial clock pin
- ICCDATA: ICC input/output serial data pin
- ICCSEL/ V_{PP} : programming voltage
- OSC1(or OSCIN): main clock input for external source (optional)
- V_{DD} : application board power supply (optional, see Figure 6, Note 3)

Figure 6. Typical ICC Interface



Notes:

1. If the ICCCLK or ICCDATA pins are only used as outputs in the application, no signal isolation is necessary. As soon as the Programming Tool is plugged to the board, even if an ICC session is not in progress, the ICCCLK and ICCDATA pins are not available for the application. If they are used as inputs by the application, isolation such as a serial resistor has to be implemented in case another device forces the signal. Refer to the Programming Tool documentation for recommended resistor values.

2. During the ICC session, the programming tool must control the $\overline{\text{RESET}}$ pin. This can lead to conflicts between the programming tool and the application reset circuit if it drives more than 5mA at high level (push pull output or pull-up resistor < 1K). A schottky diode can be used to isolate the application RESET circuit in this case. When using a classical RC network with $R > 1K$ or a reset man-

agement IC with open drain output and pull-up resistor > 1K, no additional components are needed. In all cases the user must ensure that no external reset is generated by the application during the ICC session.

3. The use of Pin 7 of the ICC connector depends on the Programming Tool architecture. This pin must be connected when using most ST Programming Tools (it is used to monitor the application power supply). Please refer to the Programming Tool manual.

4. Pin 9 has to be connected to the OSC1 or OSCIN pin of the ST7 when the clock is not available in the application or if the selected clock option is not programmed in the option byte. ST7 devices with multi-oscillator capability need to have OSC2 grounded in this case.

FLASH PROGRAM MEMORY (Cont'd)

4.5 ICP (In-Circuit Programming)

To perform ICP the microcontroller must be switched to ICC (In-Circuit Communication) mode by an external controller or programming tool.

Depending on the ICP code downloaded in RAM, Flash memory programming can be fully customized (number of bytes to program, program locations, or selection serial communication interface for downloading).

When using an STMicroelectronics or third-party programming tool that supports ICP and the specific microcontroller device, the user needs only to implement the ICP hardware interface on the application board (see [Figure 6](#)). For more details on the pin locations, refer to the device pinout description.

4.6 IAP (In-Application Programming)

This mode uses a BootLoader program previously stored in Sector 0 by the user (in ICP mode or by plugging the device in a programming tool).

This mode is fully controlled by user software. This allows it to be adapted to the user application, (user-defined strategy for entering programming mode, choice of communications protocol used to fetch the data to be stored, etc.). For example, it is

possible to download code from the SPI, SCI, USB or CAN interface and program it in the Flash. IAP mode can be used to program any of the Flash sectors except Sector 0, which is write/erase protected to allow recovery in case errors occur during the programming operation.

4.7 Related Documentation

For details on Flash programming and ICC protocol, refer to the ST7 Flash Programming Reference Manual and to the ST7 ICC Protocol Reference Manual.

4.7.1 Register Description

FLASH CONTROL/STATUS REGISTER (FCSR)

Read/Write

Reset Value: 0000 0000 (00h)

7							0
0	0	0	0	0	0	0	0

This register is reserved for use by Programming Tool software. It controls the Flash programming and erasing operations.

Figure 7. Flash Control/Status Register Address and Reset Value

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0029h	FCSR Reset Value	0	0	0	0	0	0	0	0

5 CENTRAL PROCESSING UNIT

5.1 INTRODUCTION

This CPU has a full 8-bit architecture and contains six internal registers allowing efficient 8-bit data manipulation.

5.2 MAIN FEATURES

- Enable executing 63 basic instructions
- Fast 8-bit by 8-bit multiply
- 17 main addressing modes (with indirect addressing mode)
- Two 8-bit index registers
- 16-bit stack pointer
- Low power HALT and WAIT modes
- Priority maskable hardware interrupts
- Non-maskable software/hardware interrupts

5.3 CPU REGISTERS

The six CPU registers shown in [Figure 1](#) are not present in the memory mapping and are accessed by specific instructions.

Accumulator (A)

The Accumulator is an 8-bit general purpose register used to hold operands and the results of the arithmetic and logic calculations and to manipulate data.

Index Registers (X and Y)

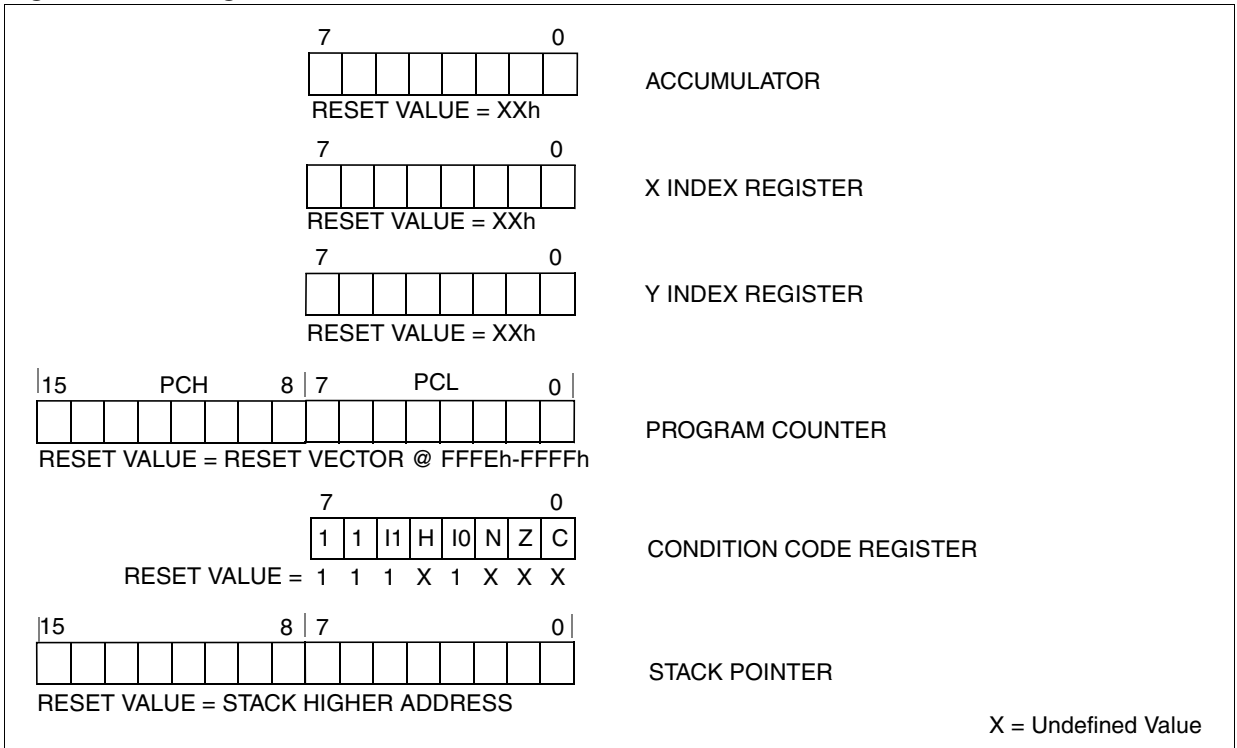
These 8-bit registers are used to create effective addresses or as temporary storage areas for data manipulation. (The Cross-Assembler generates a precede instruction (PRE) to indicate that the following instruction refers to the Y register.)

The Y register is not affected by the interrupt automatic procedures.

Program Counter (PC)

The program counter is a 16-bit register containing the address of the next instruction to be executed by the CPU. It is made of two 8-bit registers PCL (Program Counter Low which is the LSB) and PCH (Program Counter High which is the MSB).

Figure 8. CPU Registers

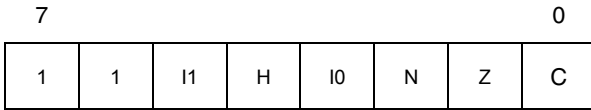


CENTRAL PROCESSING UNIT (Cont'd)

Condition Code Register (CC)

Read/Write

Reset Value: 111x1xxx



The 8-bit Condition Code register contains the interrupt masks and four flags representative of the result of the instruction just executed. This register can also be handled by the PUSH and POP instructions.

These bits can be individually tested and/or controlled by specific instructions.

Arithmetic Management Bits

Bit 4 = **H** *Half carry*.

This bit is set by hardware when a carry occurs between bits 3 and 4 of the ALU during an ADD or ADC instructions. It is reset by hardware during the same instructions.

- 0: No half carry has occurred.
- 1: A half carry has occurred.

This bit is tested using the JRH or JRNH instruction. The H bit is useful in BCD arithmetic subroutines.

Bit 2 = **N** *Negative*.

This bit is set and cleared by hardware. It is representative of the result sign of the last arithmetic, logical or data manipulation. It's a copy of the result 7th bit.

- 0: The result of the last operation is positive or null.
- 1: The result of the last operation is negative (that is, the most significant bit is a logic 1).

This bit is accessed by the JRMI and JRPL instructions.

Bit 1 = **Z** *Zero*.

This bit is set and cleared by hardware. This bit indicates that the result of the last arithmetic, logical or data manipulation is zero.

- 0: The result of the last operation is different from zero.
- 1: The result of the last operation is zero.

This bit is accessed by the JREQ and JRNE test instructions.

Bit 0 = **C** *Carry/borrow*.

This bit is set and cleared by hardware and software. It indicates an overflow or an underflow has occurred during the last arithmetic operation.

- 0: No overflow or underflow has occurred.
- 1: An overflow or underflow has occurred.

This bit is driven by the SCF and RCF instructions and tested by the JRC and JRNC instructions. It is also affected by the "bit test and branch", shift and rotate instructions.

Interrupt Management Bits

Bit 5,3 = **I1, I0** *Interrupt*

The combination of the I1 and I0 bits gives the current interrupt software priority.

Interrupt Software Priority	I1	I0
Level 0 (main)	1	0
Level 1	0	1
Level 2	0	0
Level 3 (= interrupt disable)	1	1

These two bits are set/cleared by hardware when entering in interrupt. The loaded value is given by the corresponding bits in the interrupt software priority registers (IxSPR). They can be also set/cleared by software with the RIM, SIM, IRET, HALT, WFI and PUSH/POP instructions.

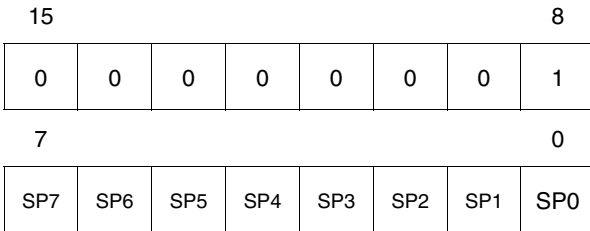
See the interrupt management chapter for more details.

CENTRAL PROCESSING UNIT (Cont'd)

Stack Pointer (SP)

Read/Write

Reset Value: 01 FFh



The Stack Pointer is a 16-bit register which is always pointing to the next free location in the stack. It is then decremented after data has been pushed onto the stack and incremented before data is popped from the stack (see Figure 2).

Since the stack is 256 bytes deep, the 8 most significant bits are forced by hardware. Following an MCU Reset, or after a Reset Stack Pointer instruction (RSP), the Stack Pointer contains its reset value (the SP7 to SP0 bits are set) which is the stack higher address.

The least significant byte of the Stack Pointer (called S) can be directly accessed by a LD instruction.

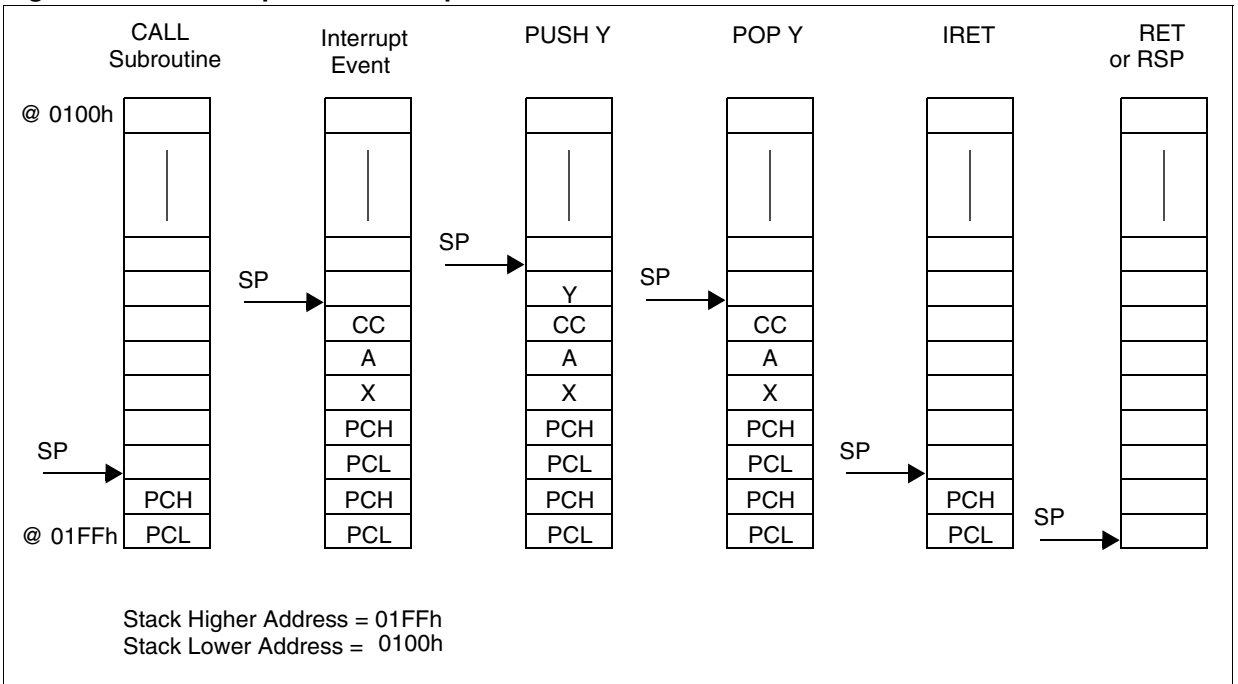
Note: When the lower limit is exceeded, the Stack Pointer wraps around to the stack upper limit, without indicating the stack overflow. The previously stored information is then overwritten and therefore lost. The stack also wraps in case of an underflow.

The stack is used to save the return address during a subroutine call and the CPU context during an interrupt. The user may also directly manipulate the stack by means of the PUSH and POP instructions. In the case of an interrupt, the PCL is stored at the first location pointed to by the SP. Then the other registers are stored in the next locations as shown in Figure 2.

- When an interrupt is received, the SP is decremented and the context is pushed on the stack.
- On return from interrupt, the SP is incremented and the context is popped from the stack.

A subroutine call occupies two locations and an interrupt five locations in the stack area.

Figure 9. Stack Manipulation Example



6 SUPPLY, RESET AND CLOCK MANAGEMENT

The device includes a range of utility features for securing the application in critical situations (for example in case of a power brown-out), and reducing the number of external components. An overview is shown in Figure 11.

For more details, refer to dedicated parametric section.

Main features

- Optional PLL for multiplying the frequency by 2 (not to be used with internal RC oscillator)
- Reset Sequence Manager (RSM)
- Multi-Oscillator Clock Management (MO)
 - 5 Crystal/Ceramic resonator oscillators
 - 1 Internal RC oscillator
- System Integrity Management (SI)
 - Main supply Low voltage detection (LVD)
 - Auxiliary Voltage detector (AVD) with interrupt capability for monitoring the main supply or the EVD pin

6.1 PHASE LOCKED LOOP

If the clock frequency input to the PLL is in the range 2 to 4 MHz, the PLL can be used to multiply the frequency by two to obtain an f_{OSC2} of 4 to 8 MHz. The PLL is enabled by option byte. If the PLL is disabled, then $f_{OSC2} = f_{OSC}/2$.

Caution: The PLL is not recommended for applications where timing accuracy is required. See “PLL Characteristics” on page 151.

Figure 10. PLL Block Diagram

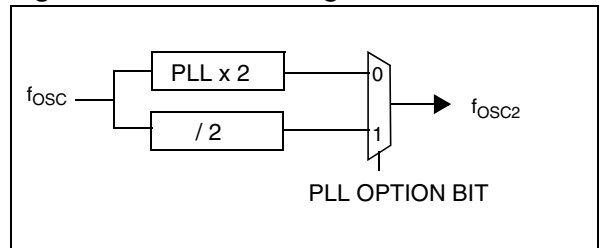
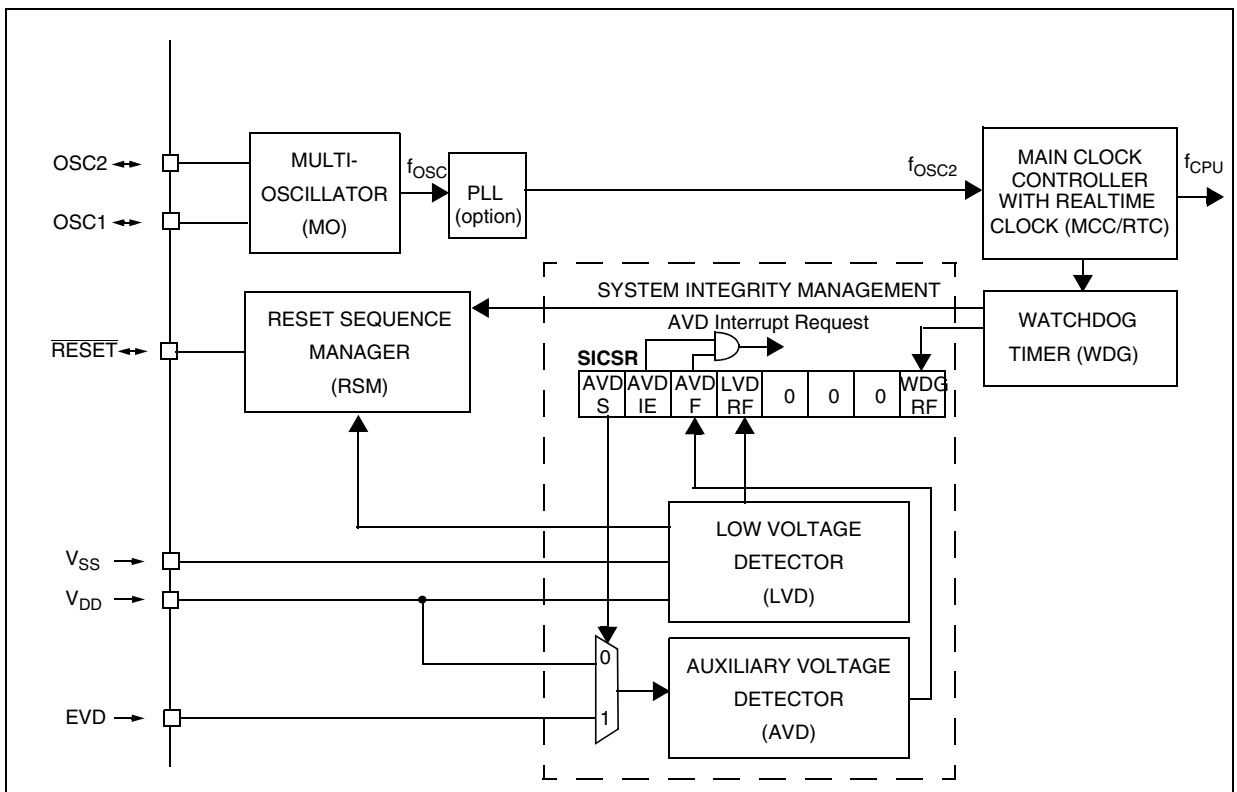


Figure 11. Clock, Reset and Supply Block Diagram



6.2 MULTI-OSCILLATOR (MO)

The main clock of the ST7 can be generated by three different source types coming from the multi-oscillator block:

- an external source
- 4 crystal or ceramic resonator oscillators
- an internal high frequency RC oscillator

Each oscillator is optimized for a given frequency range in terms of consumption and is selectable through the option byte. The associated hardware configurations are shown in [Table 5](#). Refer to the electrical characteristics section for more details.

Caution: The OSC1 and/or OSC2 pins must not be left unconnected. For the purposes of Failure Mode and Effect Analysis, it should be noted that if the OSC1 and/or OSC2 pins are left unconnected, the ST7 main oscillator may start and, in this configuration, could generate an f_{OSC} clock frequency in excess of the allowed maximum (>16MHz.), putting the ST7 in an unsafe/undefined state. The product behaviour must therefore be considered undefined when the OSC pins are left unconnected.

External Clock Source

In this external clock mode, a clock signal (square, sinus or triangle) with ~50% duty cycle has to drive the OSC1 pin while the OSC2 pin is tied to ground.

Crystal/Ceramic Oscillators

This family of oscillators has the advantage of producing a very accurate rate on the main clock of the ST7. The selection within a list of 4 oscillators with different frequency ranges has to be done by option byte in order to reduce consumption (refer to [section 14.1 on page 175](#) for more details on the frequency ranges). In this mode of the multi-oscillator, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and start-up stabilization time. The loading capacitance values must be adjusted according to the selected oscillator.

These oscillators are not stopped during the RESET phase to avoid losing time in the oscillator start-up phase.

Internal RC Oscillator

This oscillator allows a low cost solution for the main clock of the ST7 using only an internal resistor and capacitor. Internal RC oscillator mode has the drawback of a lower frequency accuracy and should not be used in applications that require accurate timing.

In this mode, the two oscillator pins have to be tied to ground.

Table 5. ST7 Clock Sources

	Hardware Configuration
External Clock	
Crystal/Ceramic Resonators	
Internal RC Oscillator	